MECHANICAL CASE OUTLINE
PACKAGE DIMENSIONS

SOT-223 (TO-261)
CASE 318E-04
ISSUE R

DATE 02 OCT 2018

NOTES:
2. CONTROLLING DIMENSION MILLIMETERS
3. DIMENSIONS D & E DO NOT INCLUDE MOLD FLASH, PROTRUSIONS OR GATE BURRS. MOLD FLASH, PROTRUSIONS OR GATE BURRS SHALL NOT EXCEED 0.200MM PER SIDE.
4. DATUMS A AND B ARE DETERMINED AT DATUM H.
5. AI IS DEFINED AS THE VERTICAL DISTANCE FROM THE SEATING PLANE TO THE LOWEST POINT OF THE PACKAGE BODY.
6. POSITIONAL TOLERANCE APPLIES TO DIMENSIONS A AND B1.

<table>
<thead>
<tr>
<th>MILLIMETERS</th>
<th>DIM</th>
<th>MIN.</th>
<th>NOM.</th>
<th>MAX.</th>
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<tbody>
<tr>
<td>A</td>
<td>1.50</td>
<td>1.63</td>
<td>1.75</td>
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<tr>
<td>A1</td>
<td>0.02</td>
<td>0.06</td>
<td>0.10</td>
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<tr>
<td>b</td>
<td>0.60</td>
<td>0.75</td>
<td>0.89</td>
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<tr>
<td>b1</td>
<td>2.90</td>
<td>3.06</td>
<td>3.20</td>
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<tr>
<td>c</td>
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<td>0.29</td>
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<tr>
<td>D</td>
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<td>6.50</td>
<td>6.70</td>
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<tr>
<td>E</td>
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<td>3.50</td>
<td>3.70</td>
<td></td>
</tr>
<tr>
<td>e</td>
<td>2.30</td>
<td>2.30</td>
<td>BSC</td>
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<tr>
<td>L</td>
<td>0.20</td>
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<td></td>
<td></td>
</tr>
<tr>
<td>L1</td>
<td>1.50</td>
<td>1.75</td>
<td>2.00</td>
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</tr>
<tr>
<td>He</td>
<td>6.70</td>
<td>7.00</td>
<td>7.30</td>
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</tr>
<tr>
<td>θ</td>
<td>0°</td>
<td></td>
<td>10°</td>
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</tbody>
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RECOMMENDED MOUNTING FOOTPRINT

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STYLE 1:
PIN 1. BASE
2. COLLECTOR
3. EMITTER
4. COLLECTOR

STYLE 2:
PIN 1. ANODE
2. CATHODE
3. NC
4. CATHODE

STYLE 3:
PIN 1. GATE
2. DRAIN
3. SOURCE
4. DRAIN

STYLE 4:
PIN 1. SOURCE
2. DRAIN
3. GATE
4. SOURCE

STYLE 5:
PIN 1. DRAIN
2. GATE
3. SOURCE
4. DRAIN

STYLE 6:
PIN 1. RETURN
2. INPUT
3. OUTPUT
4. INPUT

STYLE 7:
PIN 1. ANODE 1
2. CATHODE
3. ANODE 2
4. CATHODE

STYLE 8:
CANCELLED

STYLE 9:
PIN 1. INPUT
2. GROUND
3. LOGIC
4. GROUND

STYLE 10:
PIN 1. CATHODE
2. ANODE
3. GATE
4. ANODE

STYLE 11:
PIN 1. MT 1
2. MT 2
3. GATE
4. MT 2

STYLE 12:
PIN 1. INPUT
2. OUTPUT
3. NC
4. OUTPUT

STYLE 13:
PIN 1. GATE
2. COLLECTOR
3. EMITTER
4. COLLECTOR

GENERIC MARKING DIAGRAM*

AYW
XXXXX

A = Assembly Location
Y = Year
W = Work Week
XXXXX = Specific Device Code
* = Pb–Free Package

(Note: Microdot may be in either location)

*This information is generic. Please refer to device data sheet for actual part marking. Pb–Free indicator, “G” or microdot “*”, may or may not be present. Some products may not follow the Generic Marking.

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